



SOT1092-4

plastic thermal enhanced very thin quad flat package; no leads; 36 terminals; body 6 mm x 6 mm x 0.85 mm

20 September 2017

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN36
Package type industry code	HVQFN36
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	3-10-2016
Manufacturer package code	SOT1092-4

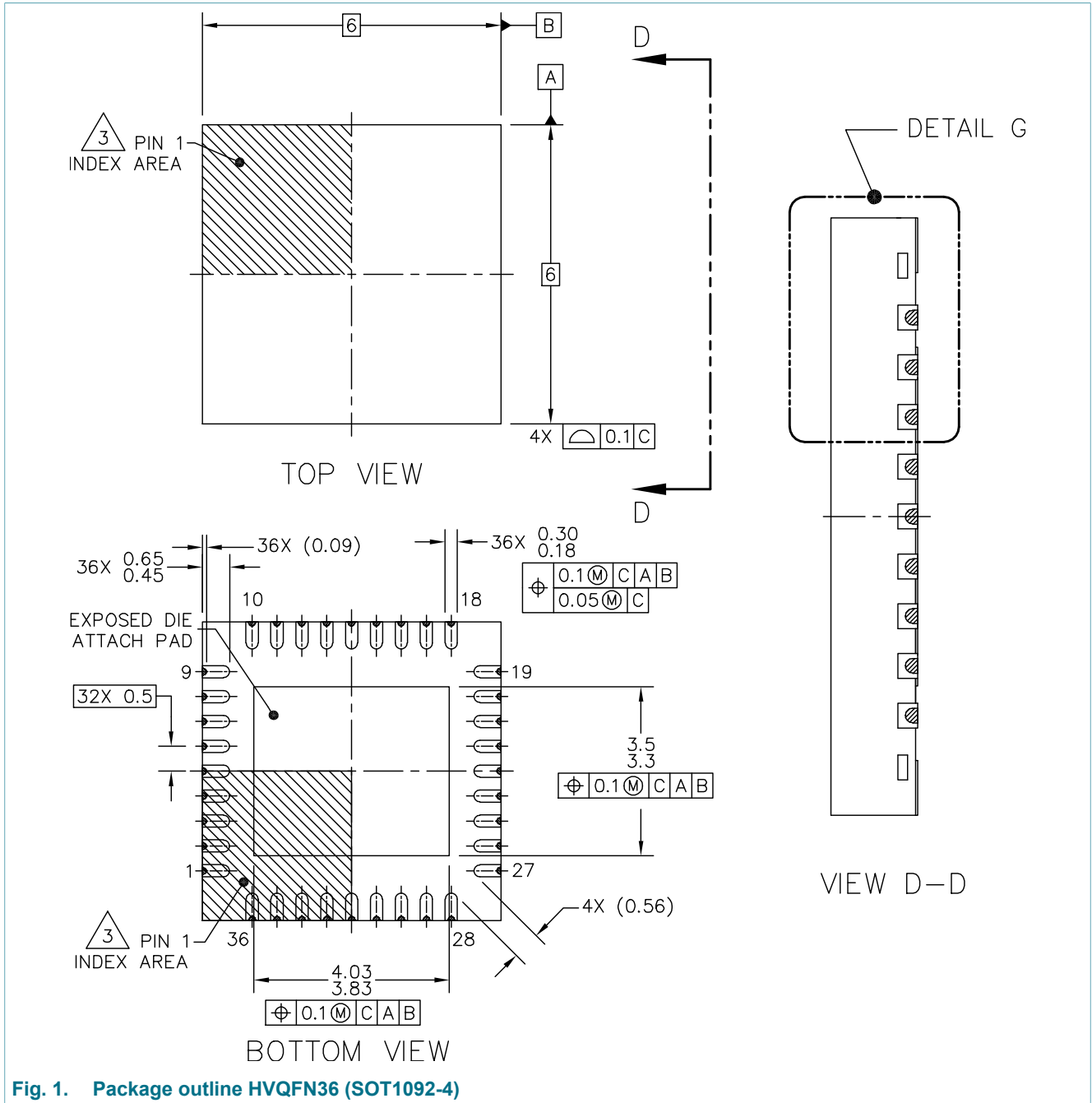
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.9	-	6	6.1	mm
E	package width	5.9	-	6	6.1	mm
A	seated height	0.8	-	0.85	1	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	36	-	A/A



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2. Package outline



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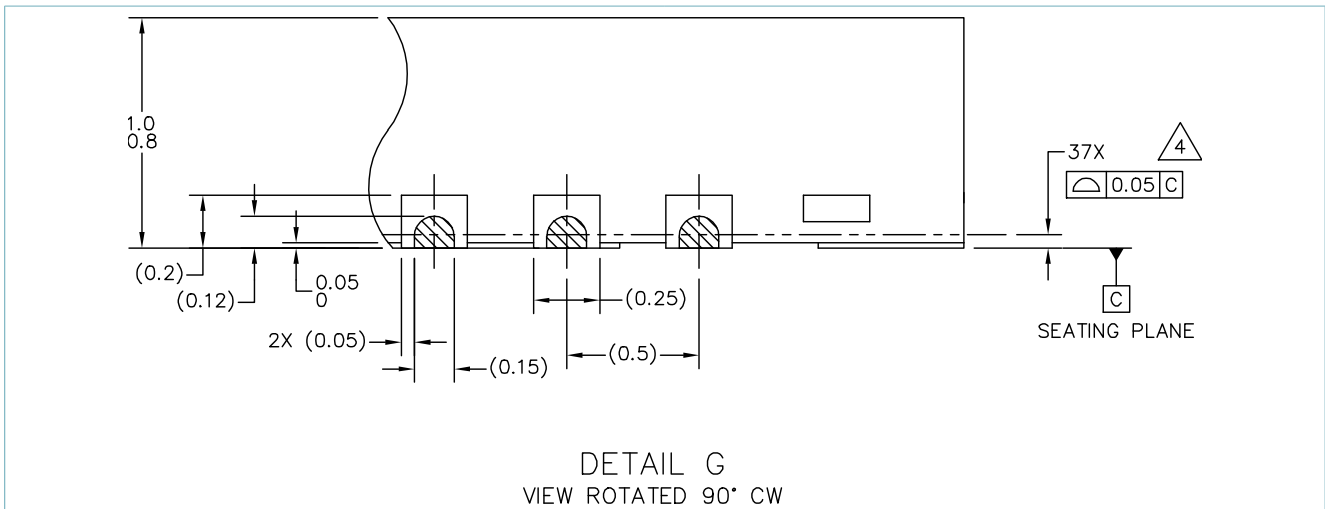


Fig. 2. Package outline dt1 HVQFN (SOT1092-4)

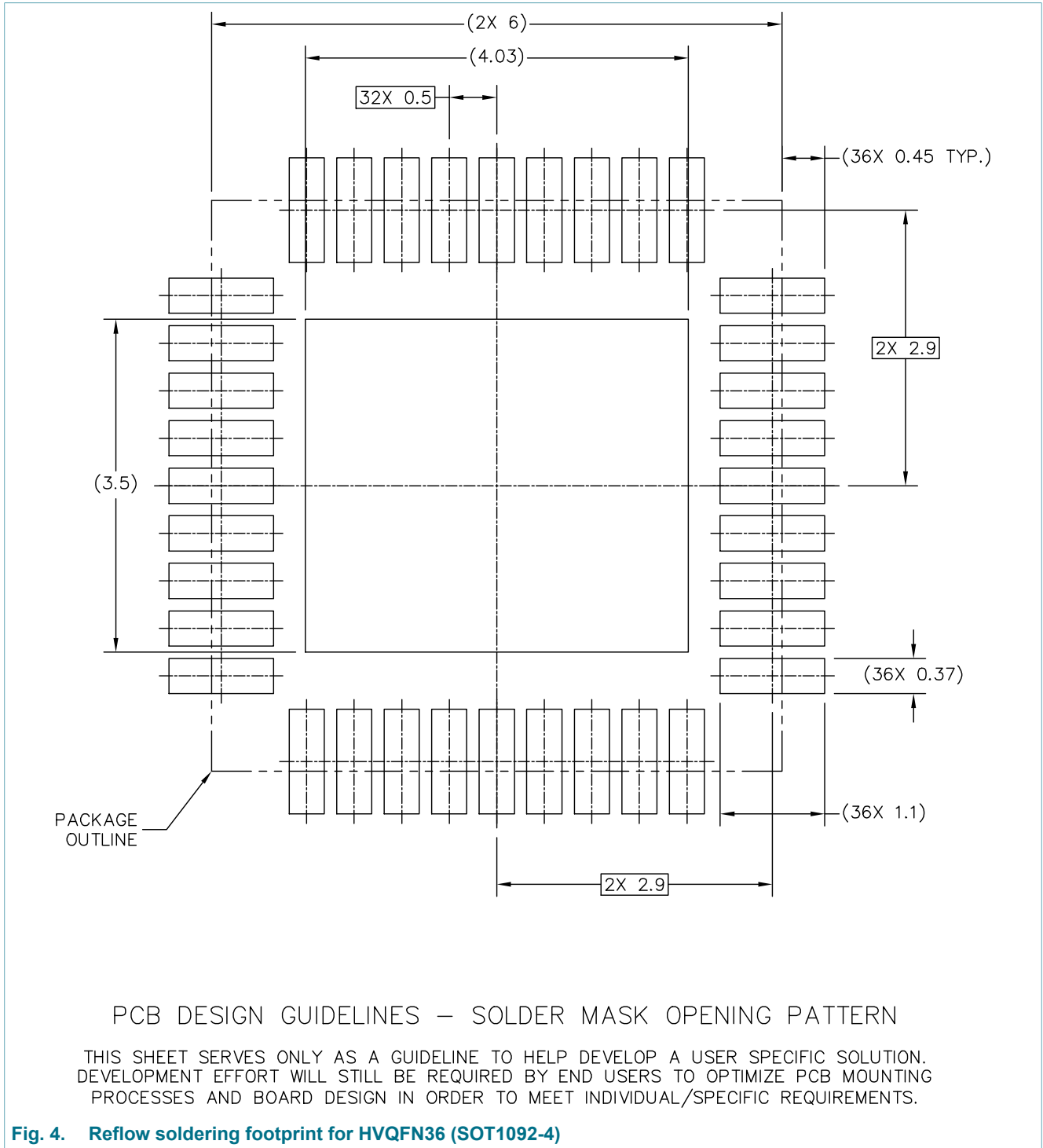
NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN ONE CONFIGURATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.25 MM.

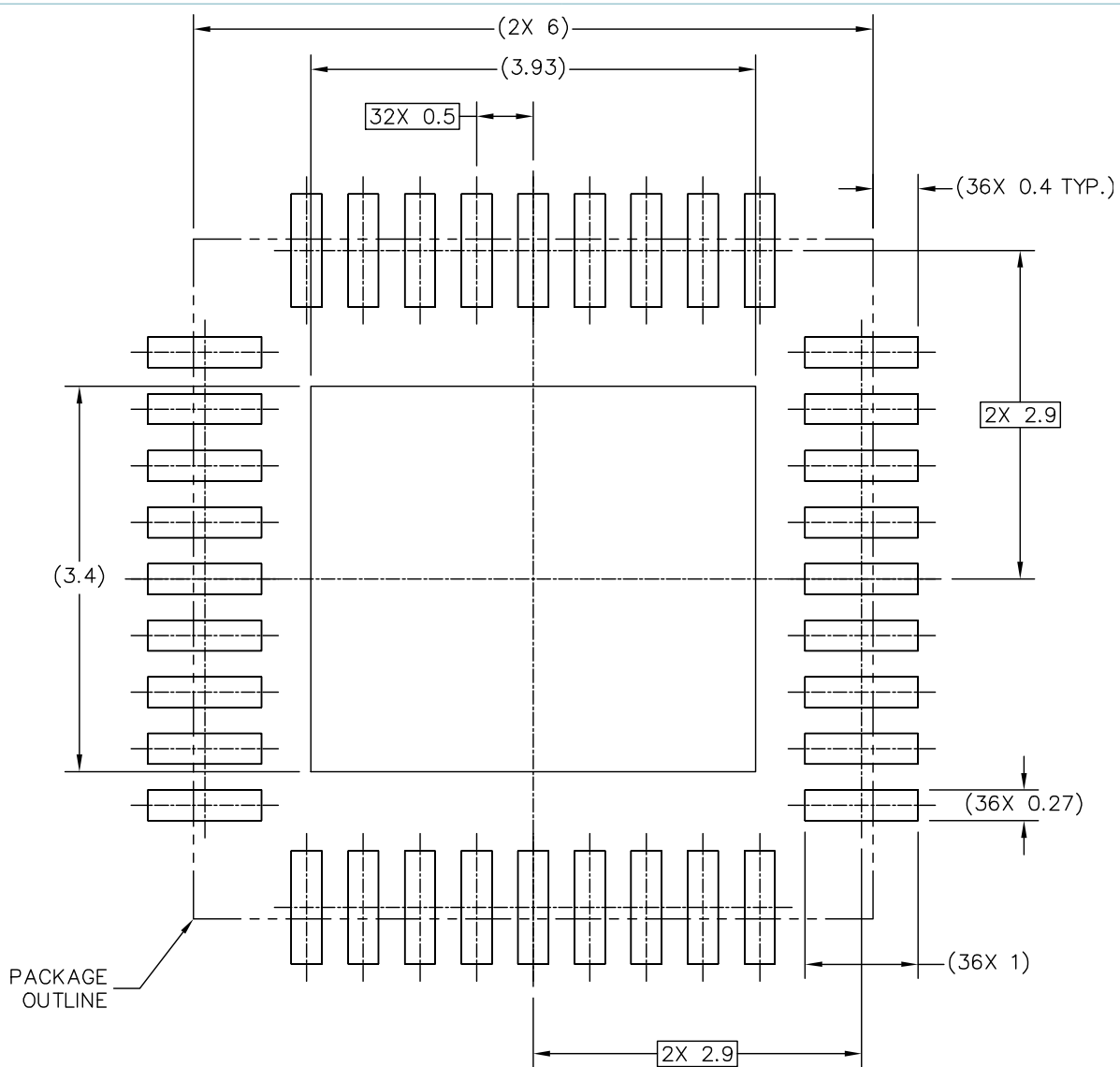
Fig. 3. Package outline note HVQFN (SOT1092-4)

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3. Soldering



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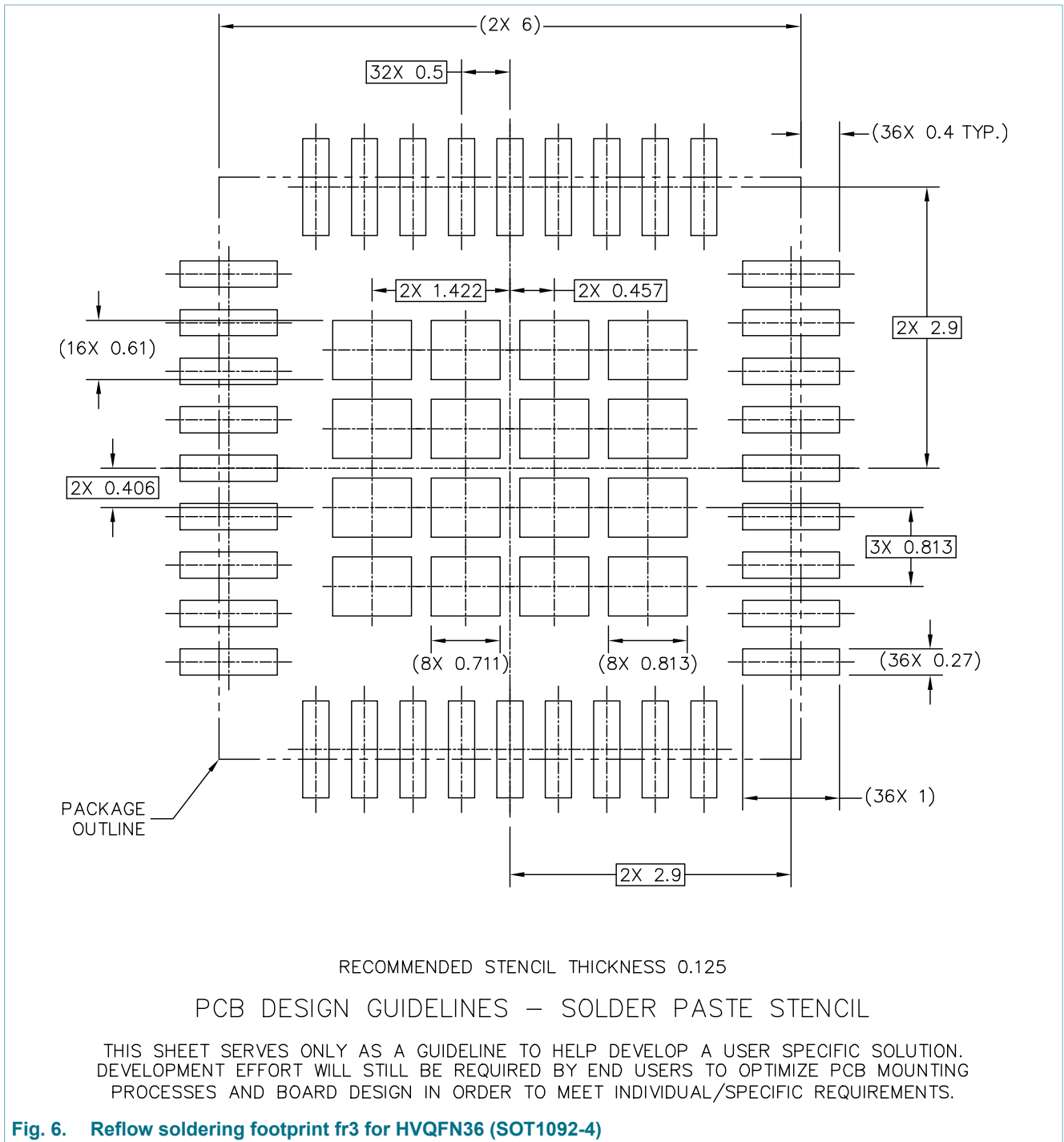


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Fig. 5. Reflow soldering footprint fr2 for HVQFN36 (SOT1092-4)

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4. Legal information

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